

What is claimed is:

1. A socket or adapter device, comprising at least one connection pin, the connection pin configured to be connected to a corresponding contact device of a device,
5 wherein
the connection pin is configured to be connected to the contact device by solderless surface mounting.
- 10 2. The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing socket or a semiconductor device testing adapter, respectively, which is configured for testing a semiconductor device such that it can be loaded with a corresponding semiconductor device.
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3. The socket or adapter device according to claim 2, wherein the socket or adapter device is a burn-in testing socket or a burn-in testing adapter, respectively, which is
20 configured for performing a burn-in test and can be loaded with a corresponding semiconductor device.
4. The socket or adapter device according to claim 1, wherein the connection pin is made of a flexible or resilient material.
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5. The socket or adapter device according to claim 4, wherein the metal alloy includes copper and/or beryllium.
- 30 6. The socket or adapter device according to claim 1, wherein at least one section of the connection pin has an arcuate or bent shape.

7. The socket or adapter device according to claim 1,
wherein the device comprising the contact device is a cir-
cuit board configured to be connected to a testing appara-
tus.

8. The socket or adapter device according to claim 1,
wherein the device comprising the contact device is a test-
ing apparatus.

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9. A system, comprising:
at least one socket or adapter device; and
at least one semiconductor device testing apparatus or
at least one circuit board, wherein

15 the socket or adapter device comprises at least one
connection pin which is configured to be connected to a cor-
responding contact device for connection to the testing ap-
paratus or to the circuit board that can be connected with a
testing apparatus, and

20 the connection pin is connected to the contact device
by surface mounting.

10. The system according to claim 9, wherein the connection
pin is connected to the contact device without soldering.

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11. The system according to claim 9, wherein a device is
provided such that the connection pin is pressed against the
contact device.

30 12. The system according to claim 11, wherein the device is
an appropriate screw connection.

13. The system according to claim 11, wherein the device is an appropriate clamping connection.

14. The system according to claim 10, wherein the socket or
5 adapter device comprises a plurality of connection pins, each being connected to corresponding contact device, and wherein the connection pins each are connected to the respectively corresponding contact devices without soldering.

10 15. A method for testing semiconductor devices, comprising:
connecting a socket or adapter device to a testing system, wherein at least one connection pin is connected to a corresponding contact device;
loading the socket or adapter device with a semi-
15 conductor device to be tested,
wherein the connection of the connection pin to the contact device is performed by solderless surface mounting.